

Abstract of the Disclosure

A method for joining two or more substrates with a seam is provided. The seam is formed with a thermoplastic tape that is capable of forming an adhesive bond and a physical bond with a substrate. For instance, in one embodiment, the thermoplastic tape is formed from a polyurethane film. In addition, the seam can be utilized in a flat configuration or folded into a variety of different shapes, such as in a z-shaped configuration. As a result of the present invention, it has been discovered that a seam can be formed to have improved strength without substantially sacrificing the desired functional properties of the substrate materials.